



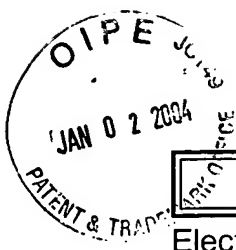
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Electronic Patent Application Submission
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Title of Invention: REINFORCED DIE PAD SUPPORT
STRUCTURE
First Named Inventor: Chung Tzu
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**TRANSMITTAL**

Electronic Version v1.1
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Title of Invention	REINFORCED DIE PAD SUPPORT STRUCTURE									
Application Number: 10/669820 										
Date: 2003-09-24										
First Named Applicant: Chung Hsing Tzu										
Confirmation Number: 5197										
Attorney Docket Number: AMKOR090										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids1-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids1-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids1-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number: 10/669820



Confirmation Number: 5197

First Named Applicant: Chung Tzu

Attorney Docket Number: AMKOR090

Art Unit: 2811

Search string: (2596993 or 3435815 or 3734660 or 3838984
or 4054238 or 4189342 or 4258381 or 4289922
or 4301464 or 4332537 or 4417266 or 4451224
or 4530152 or 4541003 or 4646710 or 4707724
or 4727633 or 4737839 or 4756080 or 4812896
or 4862245 or 4862246 or 4907067 or 4920074
or 4935803 or 4942454 or 4987475 or 5018003
or 5029386 or 5041902 or 5057900 or 5059379
or 5065223 or 5070039 or 5087961 or 5091341
or 5096852 or 5118298 or 5151039 or 5157475
or 5157480 or 5168368 or 5172213 or 5172214
or 5175060 or 5200362 or 5200809 or 5214845
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20010014538 or 20010011654 or 20020024122
or 20020027297 or 20020140061 or
20020140068 or 20020163015 or 20030030131
or 20030073265),pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Note: Applicant is not required to submit a paper copy of cited US Published Applications

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Signature

Examiner Name	Date